PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5375022

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHUEI-TANG WANG	12/21/2018
CHEN-HUA YU	12/21/2018
CHUNG-SHI LIU	12/21/2018
CHIH-YUAN CHANG	12/21/2018
JIUN-YI WU	12/25/2018
JENG-SHIEN HSIEH	12/21/2018
TIN-HAO KUO	12/22/2018

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
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City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16231622

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	02/14/2019

Total Attachments: 4
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DECLARATION AND ASSIGNMENT

FOR UTILITY OR DESIGN PATENT APPLICATION

☒ Declaration Submitted With Initial Filing

OR

☐ Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

SEMICONDUCTOR PACKAGE STRUCTURE AND MANUFACTURING METHOD THEREOF

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

☒ The attached application,

OR

☐ United States Application Number or PCT International application number

______________Filed on ________________

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

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DECLARATION AND ASSIGNMENT

FOR UTILITY OR DESIGN PATENT APPLICATION

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS, 1. **Taiwan Semiconductor Manufacturing Co., Ltd.**
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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DECLARATION AND ASSIGNMENT

FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: Chuei-Tang Wang Date: Dec. 21/2018

Legal Name of Sole or First Inventor: **Chuei-Tang Wang**

Residence: Taichung City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Date: 12/21/'18

Legal Name of Additional Joint Inventor, if any: **Chen-Hua Yu**

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Chung-Shi Liu Date: 12/21/'18

Legal Name of Additional Joint Inventor, if any: **Chung-Shi Liu**

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Chih-Yuan Chang Date: Dec 21, 2018

Legal Name of Additional Joint Inventor, if any: **Chih-Yuan Chang**

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Jiun Yi Wu Date: 12/25 '18

Legal Name of Additional Joint Inventor, if any: **Jiun-Yi Wu**

Residence: Taoyuan City, Taiwan

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DECLARATION AND ASSIGNMENT

FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: Jeng-Shien Hsieh Date: Dec 21, 2018

Legal Name of Additional Joint Inventor, if any: **Jeng-Shien Hsieh**

Residence: Kaohsiung, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Tin Hao Kuo Date: Dec 22 2018

Legal Name of Additional Joint Inventor, if any: **Tin-Hao Kuo**

Residence: Hsinchu City, Taiwan

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